

ABSTRACT OF THE DISCLOSURE

Disclosed are a polishing agent containing at least globular-silica powder and alumina powder, as well as a lapping method in which a workpiece is held between an upper turn table and a lower turn table and is lapped by rotating the upper and the lower turn tables while being supplied with a polishing agent, wherein the polishing agent supplied is the polishing agent containing at least globular-silica powder and alumina powder. Thus, there can be provided a polishing agent capable of further improving the quality, especially, the flatness of workpieces such as silicon wafers and capable of polishing the workpieces at an excellent polishing rate.